LNJ115W87RA1

Hight Bright Surface Mounting Chip LED

TSS-2 Type

■ Absolute Maximum Ratings T_a = 25°C

• Pure Green

Parameter	Symbol	Rating	Unit
Power dissipation	P_D	65	mW
Forward current	I_F	15	mA
Pulse forward current *	I_{FP}	55	mA
Reverse voltage	V_R	5	V
Operating ambient temperature	T_{opr}	–30 to +85	°C
Storage temperature	T_{stg}	–40 to +100	°C

Note) *: The condition of I_{FP} is duty 10%, Pulse width 1 msec.

• Red

Parameter	Symbol	Rating	Unit
Power dissipation	P_D	55	mW
Forward current	I_F	20	mA
Pulse forward current *	I_{FP}	60	mA
Reverse voltage	V_R	4	V
Operating ambient temperature	T_{opr}	–30 to +85	°C
Storage temperature	T_{stg}	–40 to +100	°C

Note) *: The condition of I_{FP} is duty 10%, Pulse width 1 msec.

■ Lighting Color

• Pure Green
• Red

■ Electro-Optical Characteristics T_a = 25°C±3°C

• Pure Green

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Luminous intensity *	I_O	I_F = 5 mA	15.0	40.0	110.0	mcd
Reverse current	I_R	V_R = 5 V			100	μA
Forward voltage	V_F	I_F = 5 mA		2.90	3.20	V
Peak emission wavelength	λ_P	I_F = 5 mA		520		nm
Dominant emission wavelength	λ_d	I_F = 5 mA	518	527	538	nm
Spectral half band width	$\Delta\lambda$	I_F = 5 mA		30		nm

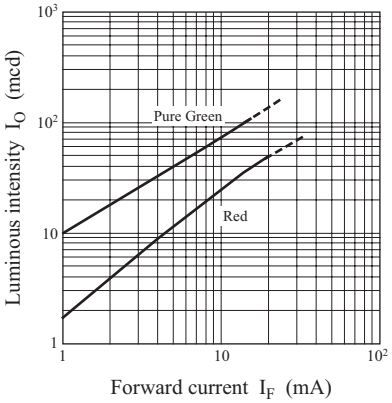
Note) *: Measurement tolerance: ±20%

• Red

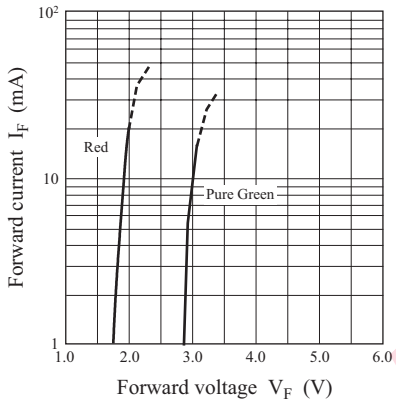
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Luminous intensity *	I_O	I_F = 10 mA	12.0	24.0	60.8	mcd
Reverse current	I_R	V_R = 4 V			100	μA
Forward voltage	V_F	I_F = 10 mA		1.92	2.50	V
Peak emission wavelength	λ_P	I_F = 10 mA		645		nm
Dominant emission wavelength	λ_d	I_F = 10 mA	620	630	640	nm
Spectral half band width	$\Delta\lambda$	I_F = 10 mA		22		nm

Note) *: Measurement tolerance: ±20%

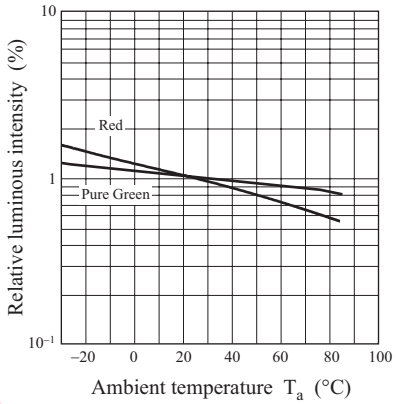
I_O — I_F



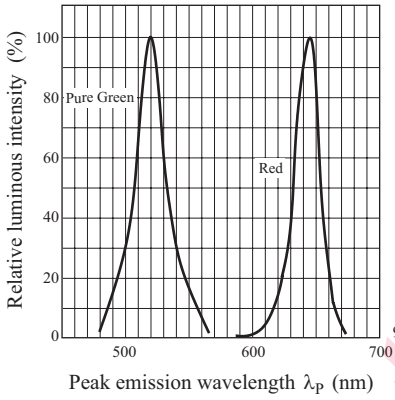
I_F — V_F



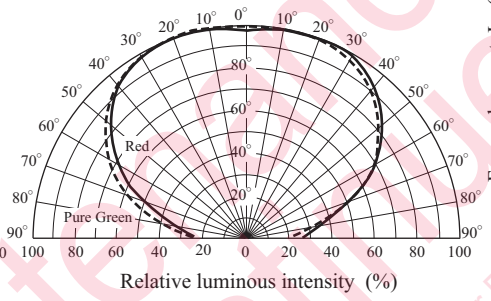
Relative luminous intensity — T_a



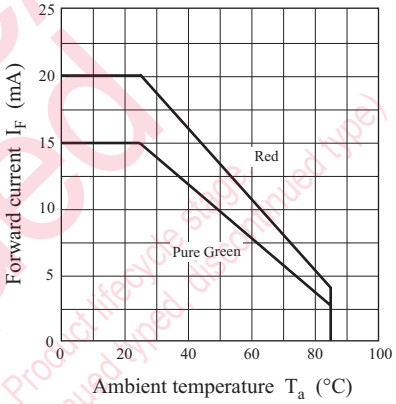
Relative luminous intensity — λ_P



Directive characteristics

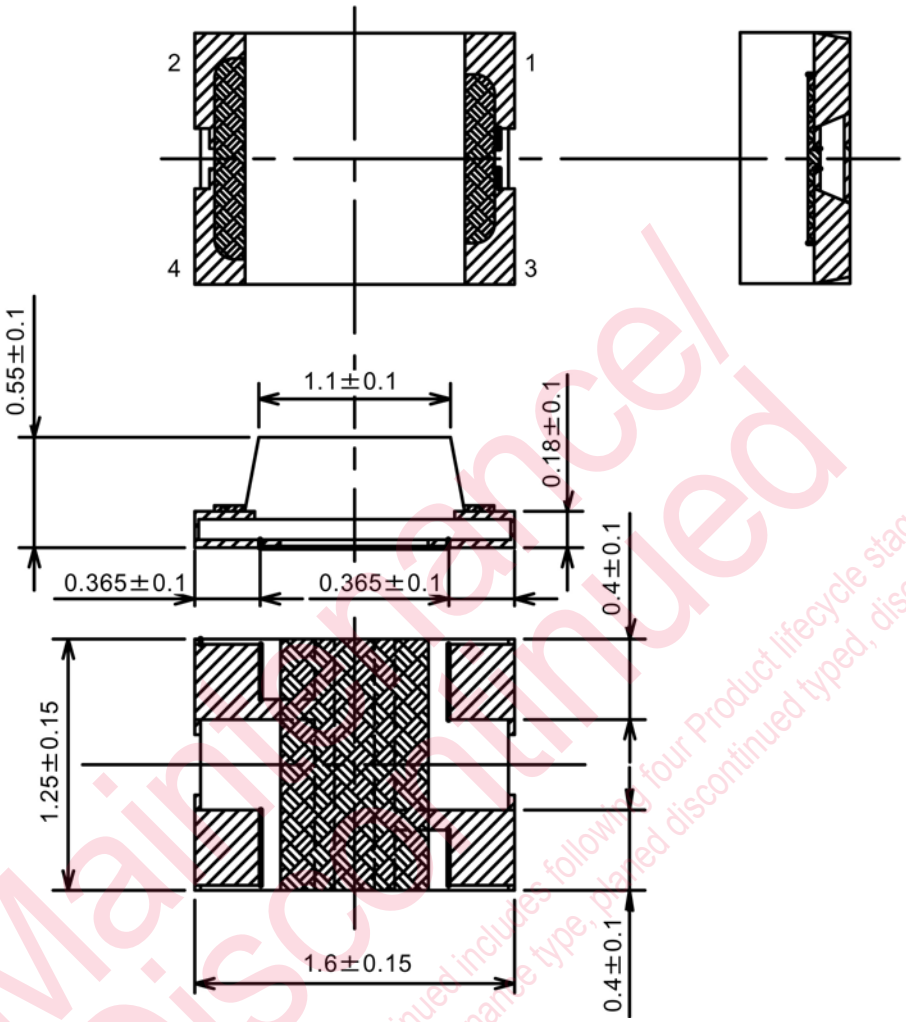


I_F — T_a



■ Package (Unit: mm)

KLTFTN4K1540



- Pin name
  1, 3: Anode
  2, 4: Cathode

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